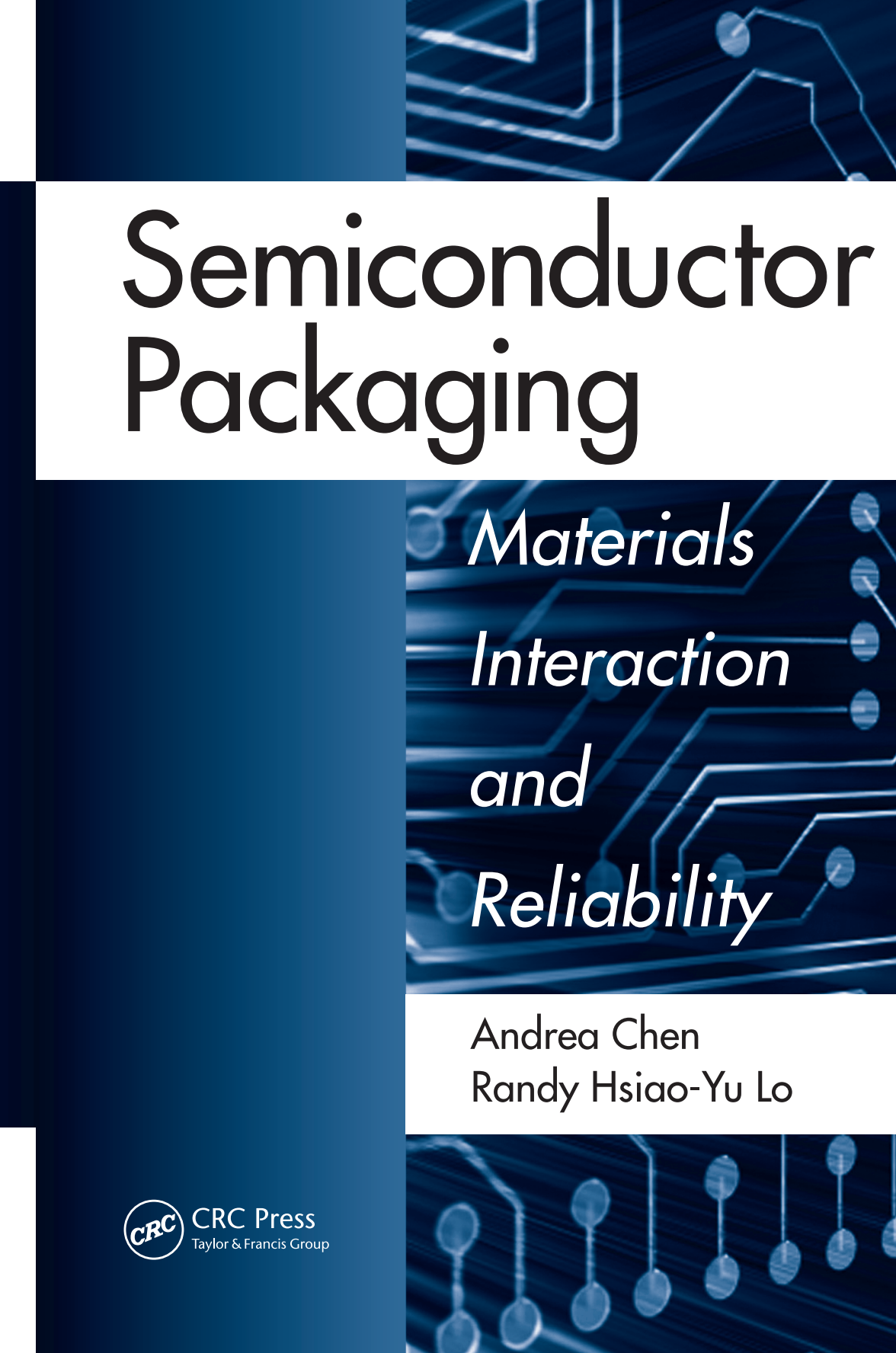




Semiconductor Packaging

*Materials
Interaction
and
Reliability*

Andrea Chen
Randy Hsiao-Yu Lo



CRC Press
Taylor & Francis Group

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